



2827

**PATENT****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Sung-Fei Wang

Serial No.: 10/087,432 Group No.: 2827

Filed: March 30, 2002 Examiner: J. Mitchell

For: Stacked semiconductor Chip Package

Attorney Docket No.: U 013887-9

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO ACTION OF JULY 30, 2003**

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